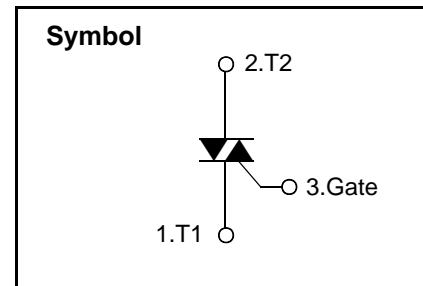
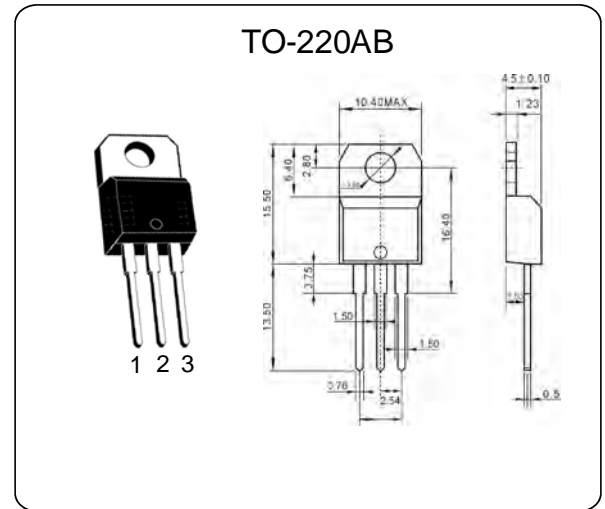


## Bi-Directional Triode Thyristor

Designed for high performance full-wave ac control applications where high noise immunity and high commutating di/dt are required.

### Features

- Blocking Voltage to 800V
- On-State Current Rating of 8A RMS at 100°C
- Uniform Gate Trigger Currents in Three Quadrants
- High Immunity to dV/dt-1500V/us minimum at 125°C
- Minimizes Snubber Networks for Protection
- Industry Standard TO-220AB Package
- High Commutating dI/dt- 4.0A/ms minimum at 125°C
- Internally Isolated (2500VRMS)
- These are Pb-Free Devices



### Absolute Maximum Ratings

Symbol	Parameter		Value	Unit
I <sub>T(RMS)</sub>	RMS on-state current(full sine wave)	TO-220AB TC=110 °C	8	A
		TO-220AB Ins. TC=100 °C		
I <sub>TSM</sub>	Non repetitive surge peak on-state current(full cycle, T <sub>j</sub> initial=25 °C)	F=50Hz t=20ms	80	A
		F=60Hz t=16.7ms	84	
I <sup>2</sup> t	I <sup>2</sup> t Value for fusing	tp=10ms	36	A <sup>2</sup> s
DI/DT	Critical rate of rise of on-state current I <sub>G</sub> =2X <sub>IGT</sub> , tr≤100ns	F=120Hz T <sub>j</sub> =125 °C	50	A/us
I <sub>GM</sub>	Peak gate current	tp=20us T <sub>j</sub> =125 °C	4	A
P <sub>G(AV)</sub>	Average gate power dissipation	T <sub>j</sub> =125 °C	1	W
T <sub>stg</sub>	Storage junction temperature range		-40 to +150	°C
T <sub>j</sub>	Operating junction temperature range		-40 to +125	



# BTA08-800C

## Electrical Characteristics(T<sub>j</sub>=25°C, unless otherwise specified)

### Snubberless™ and Logic Level(3 quadrants)

Symbol	Test conditions	Quadrant	BTA08-800C		Unit
I <sub>GT</sub> (1)	V <sub>D</sub> =12V R <sub>L</sub> =30Ω	I - II -III -IV	MAX	35	mA
V <sub>GT</sub>		I - II -III -IV	MAX	1.3	V
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> R <sub>L</sub> =3.3KΩT <sub>j</sub> =125°C	I - II -III -IV	MIN	0.2	V
I <sub>H</sub> (2)	IT=100mA		MAX	50	mA
I <sub>L</sub>	I <sub>G</sub> =1.2I <sub>GT</sub>	I - II -III -IV	MAX	70	mA
		II		80	
Dv / Dt(2)	V <sub>D</sub> =67%V <sub>DRM</sub> Gate open T <sub>j</sub> =125°C		MIN	1000	V/us
(DI/dt)c(2)	(Dv/dt)c=0.1 V/us T <sub>j</sub> =125°C		MIN	-	A/ms
	(Dv/dt)c=10V/us T <sub>j</sub> =125°C			-	
	Without snubber T <sub>j</sub> =125°C			7	

### Standard (4Quadrants)

Symbol	Test conditions	Quadrant	BTA08-800C		Unit
IGT(1)	V <sub>D</sub> =12V R <sub>L</sub> =30Ω	I - II -III	MAX	35	mA
		IV		50	
V <sub>GT</sub>		ALL	MAX	1.3	V
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> R <sub>L</sub> =3.3KΩT <sub>j</sub> =125°C	ALL	MIN	0.2	V
I <sub>H</sub> (2)	IT=500mA		MAX	50	mA
I <sub>L</sub>	I <sub>G</sub> =1.2IGT	I -III- IV	MAX	50	mA
		II		100	
(DI/dt)(2)	V <sub>D</sub> =67%V <sub>DRM</sub> Gate open T <sub>j</sub> =125°C		MIN	400	V/us
(DI/dt)c(2)	(Dv/dt)c=3.5 A/ms T <sub>j</sub> =125°C		MIN	10	V/us

### Static Characteristics

Symbol	Test conditions			Value	Unit
V <sub>TM</sub> (2)	ITM=11A tp=380us	T <sub>J</sub> =25°C	MAX	1.55	V
V <sub>to</sub> (2)	Threshold voltage	T <sub>J</sub> =125°C	MAX	0.85	V
R <sub>d</sub> (2)	Dynamic resistance	T <sub>J</sub> =125°C	MAX	50	mΩ
I <sub>DRM</sub>	V <sub>DRM</sub> =V <sub>R<sub>RRM</sub></sub>	T <sub>J</sub> =25°C		5	uA
I <sub>R<sub>RRM</sub></sub>		T <sub>J</sub> =125°C	MAX	1	mA
V <sub>DRM</sub> /V <sub>R<sub>RRM</sub></sub>	Voltage	T <sub>J</sub> =25°C	MIN	800	V

Note 1: minimum IGT is guaranteed at 5% of IGT max

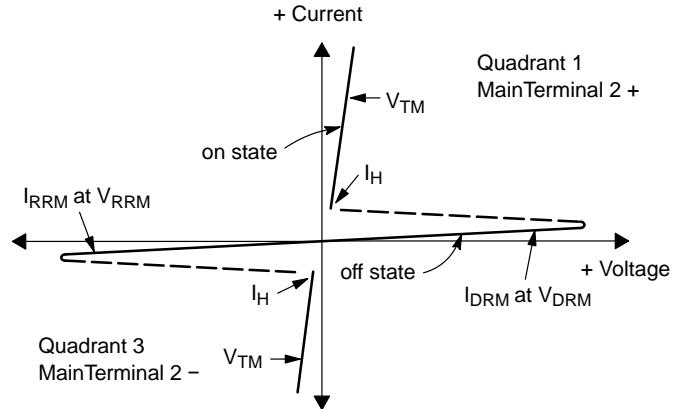
Note 2: for both polarities of A2 referenced to A1

### Thermal Resistances

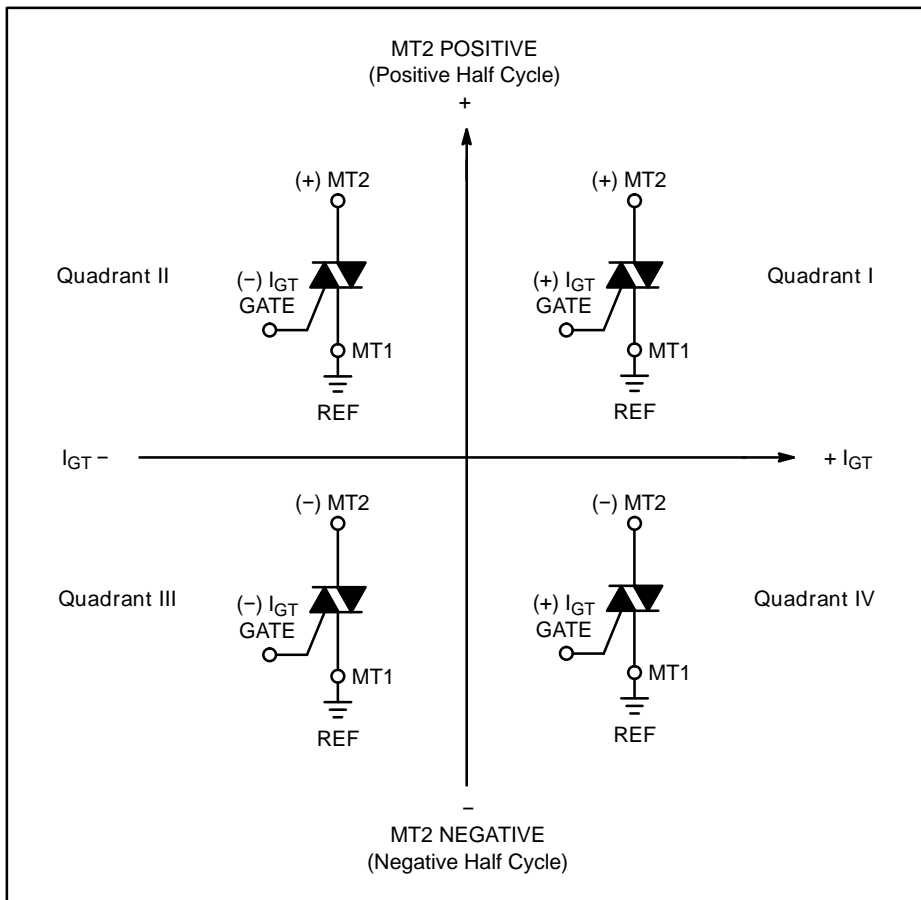
Symbol	Parameter		Value	Unit
R <sub>th(j-c)</sub>	Junction to case(AC)	TO-220AB	1.6	°C/W
		TO-220AB(Insulated)	2.5	
R <sub>th(j-a)</sub>	Junction to ambient	TO-220AB/ TO-220AB(Insulated)	60	°C/W

## Voltage Current Characteristic of Triacs (Bidirectional Device)

Symbol	Parameter
$V_{DRM}$	Peak Repetitive Forward Off State Voltage
$I_{DRM}$	Peak Forward Blocking Current
$V_{RRM}$	Peak Repetitive Reverse Off State Voltage
$I_{RRM}$	Peak Reverse Blocking Current
$V_{TM}$	Maximum On State Voltage
$I_H$	Holding Current



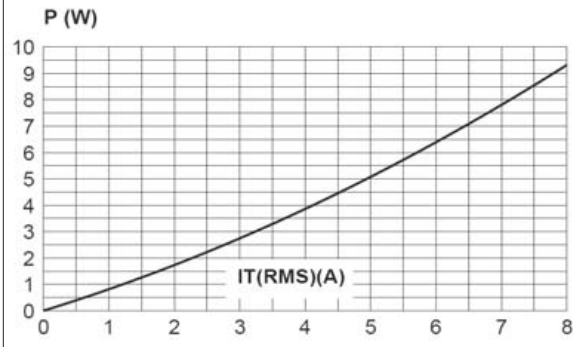
### Quadrant Definitions for a Triac



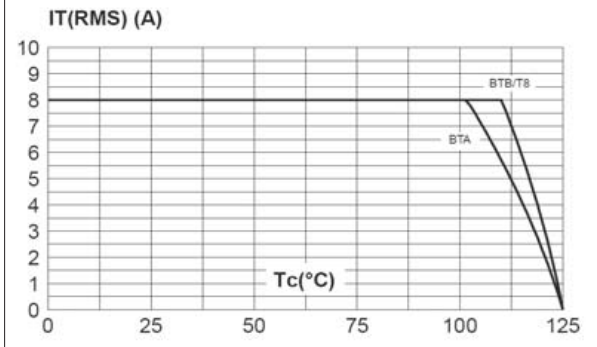
All polarities are referenced to MT1.  
 With in-phase signals (using standard AC lines) quadrants I and III are used.

## Description

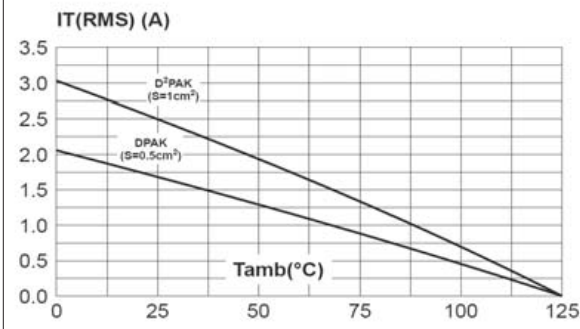
**Fig. 1:** Maximum power dissipation versus RMS on-state current (full cycle).



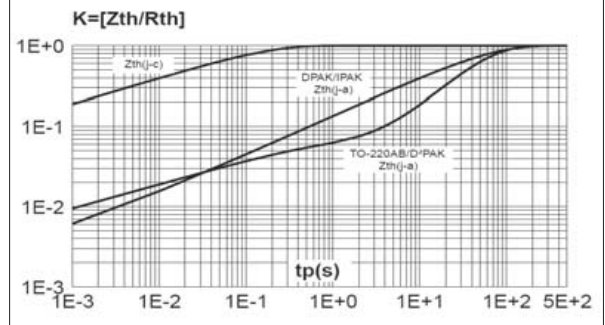
**Fig. 2-1:** RMS on-state current versus case temperature (full cycle).



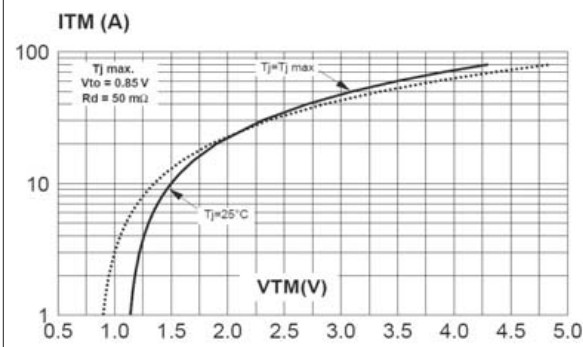
**Fig. 2-2:** RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness: 35µm), full cycle.



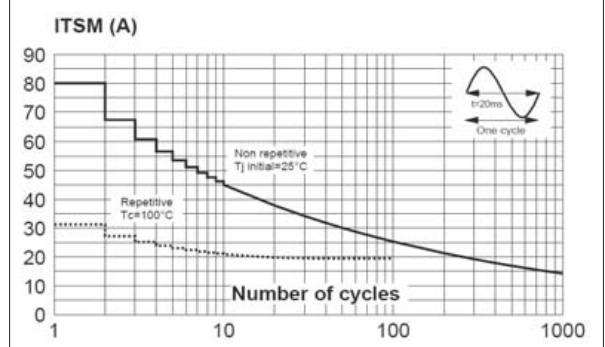
**Fig. 3:** Relative variation of thermal impedance versus pulse duration.



**Fig. 4:** On-state characteristics (maximum values).

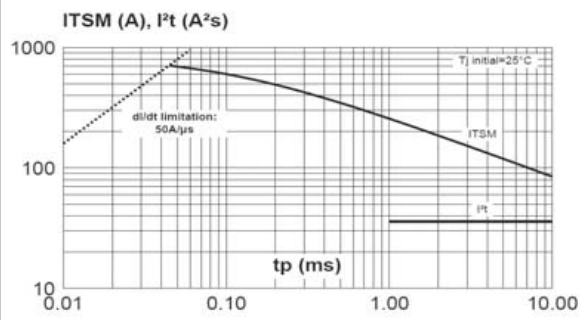


**Fig. 5:** Surge peak on-state current versus number of cycles.

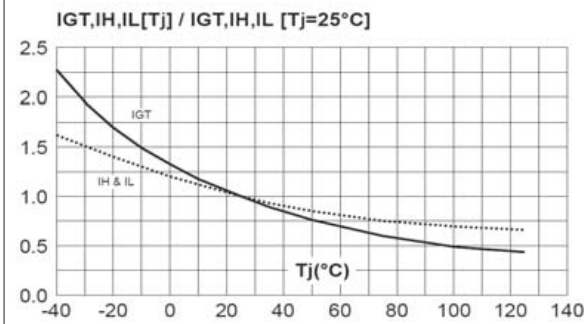


# Description

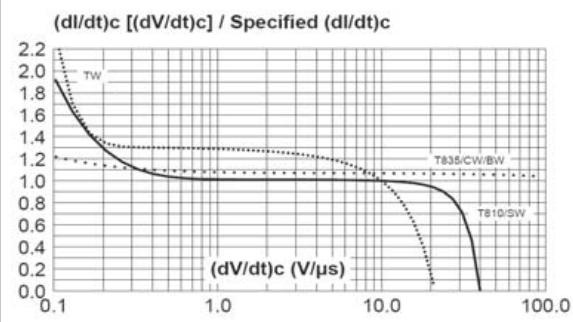
**Fig. 6:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 10\text{ms}$ , and corresponding value of  $I^2t$ .



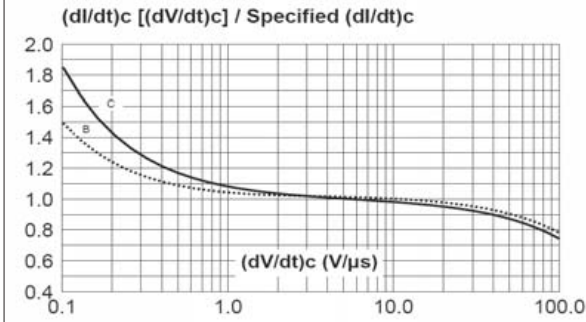
**Fig. 7:** Relative variation of gate trigger current, holding current and latching current versus junction temperature (typical values).



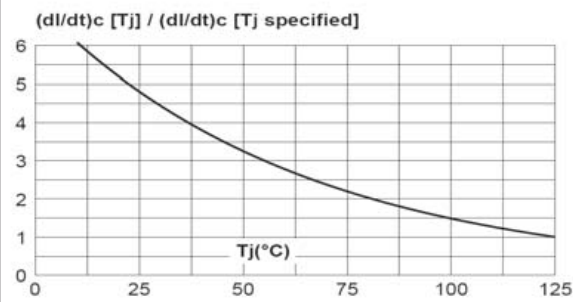
**Fig. 8-1:** Relative variation of critical rate of decrease of main current versus  $(dV/dt)_c$  (typical values). Snubberless & Logic Level Types



**Fig. 8-2:** Relative variation of critical rate of decrease of main current versus  $(dV/dt)_c$  (typical values). Standard Types



**Fig. 9:** Relative variation of critical rate of decrease of main current versus junction temperature.



**Fig. 10:** DPAK and D<sup>2</sup>PAK Thermal resistance junction to ambient versus copper surface under tab (printed circuit board FR4, copper thickness: 35 μm).

